L Number		Search Text	DB	Time stamp
-	9015	(438/106-127).CCLS.	USPAT;	2004/08/10 14:26
			US-PGPUB;	
			EPO; JPO; DERWENT;	
İ			IBM TDB	
_	0	((438/106-127).CCLS.) and ((SiC or carbide)	USPAT;	2004/08/10 14:27
	Ū	with die) and (BPSG with (adhesive or	US-PGPUB;	
		encapsul\$6)) and AlN	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	((438/106-127).CCLS.) and ((SiC or carbide)	USPAT;	2004/08/10 14:27
		with die) and (BPSG with (adhesive or	US-PGPUB;	
		encapsul\$6))	EPO; JPO;	
			DERWENT;	! !
	0	((438/106-127).CCLS.) and (SiC or carbide)	IBM_TDB USPAT;	2004/08/10 14:27
_	U	and (BPSG with (adhesive or encapsul\$6))	US-PGPUB;	2004/08/10 14:2/
		and (BF36 with (addesive of encapsary))	EPO; JPO;	
			DERWENT;	1
1			IBM TDB	1
_	264	((438/106-127).CCLS.) and (SiC or carbide)	USPAT;	2004/08/10 14:28
		and ((adhesive or encapsul\$6))	US-PGPUB;	
		_	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	37	1 ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2004/08/10 14:27
		and ((adhesive or encapsul\$6))) and AlN	US-PGPUB;	
			EPO; JPO;	1
ļ			DERWENT; IBM TDB	
_	16	((438/106-127).CCLS.) and ((SiC or carbide)	USPAT;	2004/08/10 14:28
-	10	with die) and ((adhesive or encapsul\$6))	US-PGPUB;	2004/08/10 14:28
		with die, and ((adhesive of cheapsdipo))	EPO; JPO;	l i
į			DERWENT;	
			IBM TDB	
-	0	((SiC or carbide) with die) and (BPSG with	USPAT;	2004/09/13 17:19
		(adhesive or encapsul\$6)) and AlN	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	((0)0 - 1 1 1 1 1 1 1 1 1 1	IBM_TDB	0004/00/10 17 00
-	1	((SiC or carbide) with die) and (BPSG) and	USPAT; US-PGPUB;	2004/09/13 17:38
		Aln	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	("5909354" "5981913").PN.	USPAT	2004/09/13 17:22
-	ō	((SiC or carbide)) and (BPSG) and (AlN with	USPAT;	2004/09/13 17:38
		adhesive)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		//016	IBM_TDB	0004/00/5
-	108	((SiC or carbide)) and (BPSG) and AlN	USPAT;	2004/09/14 11:10
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	4	((SiC or carbide)) and (doped adj glass) and	USPAT;	2004/09/14 11:21
	*	AlN	US-PGPUB;	
			EPO; JPO;	
j			DERWENT;	
			IBM_TDB	
-	64	SiC with metal with junction	USPAT;	2004/09/14 14:04
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	(#6210757#) PM	IBM_TDB	0004/00/24 == 0=
-	2	("6319757").PN.	USPAT;	2004/09/14 16:00
ŀ			US-PGPUB;	
].			EPO; JPO; DERWENT;	
		l	IBM_TDB	l l

-	27268	(257/678-733).CCLS.	USPAT;	2004/09/14 16:	01
			US-PGPUB; EPO; JPO;		
	ļ		DERWENT;		ŀ
	16	((257/678-733).CCLS.) and (((silicon adj	IBM_TDB USPAT;	 2004/09/14 17::	39
	40	carbide) or SiC) with die)	US-PGPUB;	2004,03,11 17.	ر
			EPO; JPO;		
			DERWENT; IBM TDB		
_	31	chip and (adhesive with (BSG or	USPAT;	2004/09/14 18:	22
İ		borosilicate))	US-PGPUB;		
			EPO; JPO; DERWENT;		
			IBM_TDB		
-	0	chip and ((gold or Au) same ((silicon adj	USPAT;	2004/09/14 17:	42
		carbide) or SiC)) same ((adhesive with (BSG or borosilicate)))	US-PGPUB; EPO; JPO;		
		or borosificace,,,	DERWENT;		
			IBM_TDB		_
-	55	chip and ((SiC or (silicon adj carbide)) with (BSG or borosilicate))	USPAT; US-PGPUB;	2004/09/14 18:	23
İ	İ	with (bbs of bolobilicate),	EPO; JPO;		
			DERWENT;		
_	4	 ("4695733" "5025243" "5122668"	IBM_TDB USPAT	2004/09/14 18:	31
	•	"5868497").PN.		2001,00,11 201.	-
-	3	(thermal with conductive with properties	USPAT;	2004/09/15 10:	15
		with (gold or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))	US-PGPUB; EPO; JPO;		
		or copper or ca, with (practina cr ro,)	DERWENT;		
			IBM_TDB	0004/00/15 10	_
-	12	(thermal with conductive with electrical with (gold or Au or aluminum or Al or nickel	USPAT; US-PGPUB;	2004/09/15 10:	33
		or copper or Cu) with (platinum or Pt))	EPO; JPO;		
			DERWENT;		
_	23	(thermal with electrically with (gold or Au	IBM_TDB USPAT;	2004/09/15 10::	34
İ		or aluminum or Al or nickel or copper or Cu)	US-PGPUB;		_
		with (platinum or Pt))	EPO; JPO;		
			DERWENT; IBM TDB		
-	169		USPĀT;	2004/09/15 10:	34
		Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))	US-PGPUB; EPO; JPO;		
		cu, with (practitum of FC))	DERWENT;		
		///	IBM_TDB	0004/00/77 75	ا ءِ
-	157	((thermal\$3 with electrical\$3 with (gold or Au or aluminum or Al or nickel or copper or	USPAT; US-PGPUB;	2004/09/15 10::	35
		Cu) with (platinum or Pt))) not ((thermal	EPO; JPO;		
		with conductive with electrical with (gold	DERWENT;		
	,	or Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt)))	IBM_TDB		
-	60	(((thermal\$3 with electrical\$3 with (gold or	USPAT;	2004/09/15 14:	23
		Au or aluminum or Al or nickel or copper or Cu) with (platinum or Pt))) not ((thermal	US-PGPUB; EPO; JPO;		
		with conductive with electrical with (gold	DERWENT;		
		or Au or aluminum or Al or nickel or copper	IBM_TDB		
		or Cu) with (platinum or Pt)))) and semiconduct\$5			
-	0	borosilica with encapsula\$4	USPAT;	2004/09/15 14:3	25
			US-PGPUB;		
			EPO; JPO; DERWENT;		
			IBM_TDB		
-	0	borosilica with encapsula\$6	USPAT;	2004/09/15 14:3	25
			US-PGPUB; EPO; JPO;		ļ
			DERWENT;		
L	1		IBM_TDB		

-	4	bsg with encapsula\$6	USPAT;	2004/09/15 14:25
			US-PGPUB;	l i
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	89	(bsg or borosilicate) with encapsula\$6	USPAT;	2004/09/15 17:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	197	(buried adj oxide) and (deep with source	USPAT;	2004/09/15 17:11
		with drain)	US-PGPUB;	! !
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	